

Tin Whisker Monitor Report

SUBCON	ISPL	
COVERAGE	2006 QTR 4	
DEVICE	MAX1556E1B	TDFN 3X3
DATE SAMPLED	30 NOV, 2006	

I. PLATING WORKMANSHIP SUMMARY

PLATING CHEMISTRY	NFEP TECHNIC
FINISH	MATTE
PLATING THICKNESS	550 micro inch

II. WHISKER TEST SUMMARY

TEST	READOUT1		READOUT2		READOUT3	
ROOM TEMP STORAGE 30°C / 60%RH	1000 H (FEB 8)		2000 H (MAR 22)		3000H (MAY 3)	
	0 / 5	0 growth	0 / 5	< 5 um	0/5	< 5 um
TEMP/ HUMIDITY STORAGE 60°C / 85%RH	1000 H (FEB 8)		2000 H (MAR 22)		3000H (MAY 3)	
	0 / 5	0 growth	0 / 5	< 5 um	0/5	< 5 um
TEMP CYCLING 85°C / -55°C	500 C (JAN 29)		1000 C *		1500 C	
	0 / 5	0 growth				

- EQUIPMENT BREAKDOWN FEB17 2007. ACTUAL CYCLES COMPLETED IS 788. SUSPENDED UNTIL FURTHER NOTICE.
- REPLACEMENT PART CURRENTLY UNAVAILABLE. EXPECTED EQUIPMENT REPAIR 3RD QTR OF 2007

III. METHODOLOGY

INSPECTION METHOD : 100X MAGNIFICATION, NO LESS THAN 6 LEADS PER PACKAGE

SAMPLING FREQUENCY : 1 LOT / 3 MONTHS

SAMPLE SIZE : 5 UNITS PER TEST CONDITION

FAILURE CRITERIA : > 40 μm